

SOT1879-2

LFBGA393, plastic, low profile fine-pitch ball grid array; 393 balls; 0.5 mm pitch; 14 mm x 14 mm x 1.38 mm body

25 June 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA393
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-06-2017
Manufacturer package code	98ASA01091D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	14	-	mm
package width	-	14	-	mm
package height	-	1.38	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	393	-	



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2 Package outline

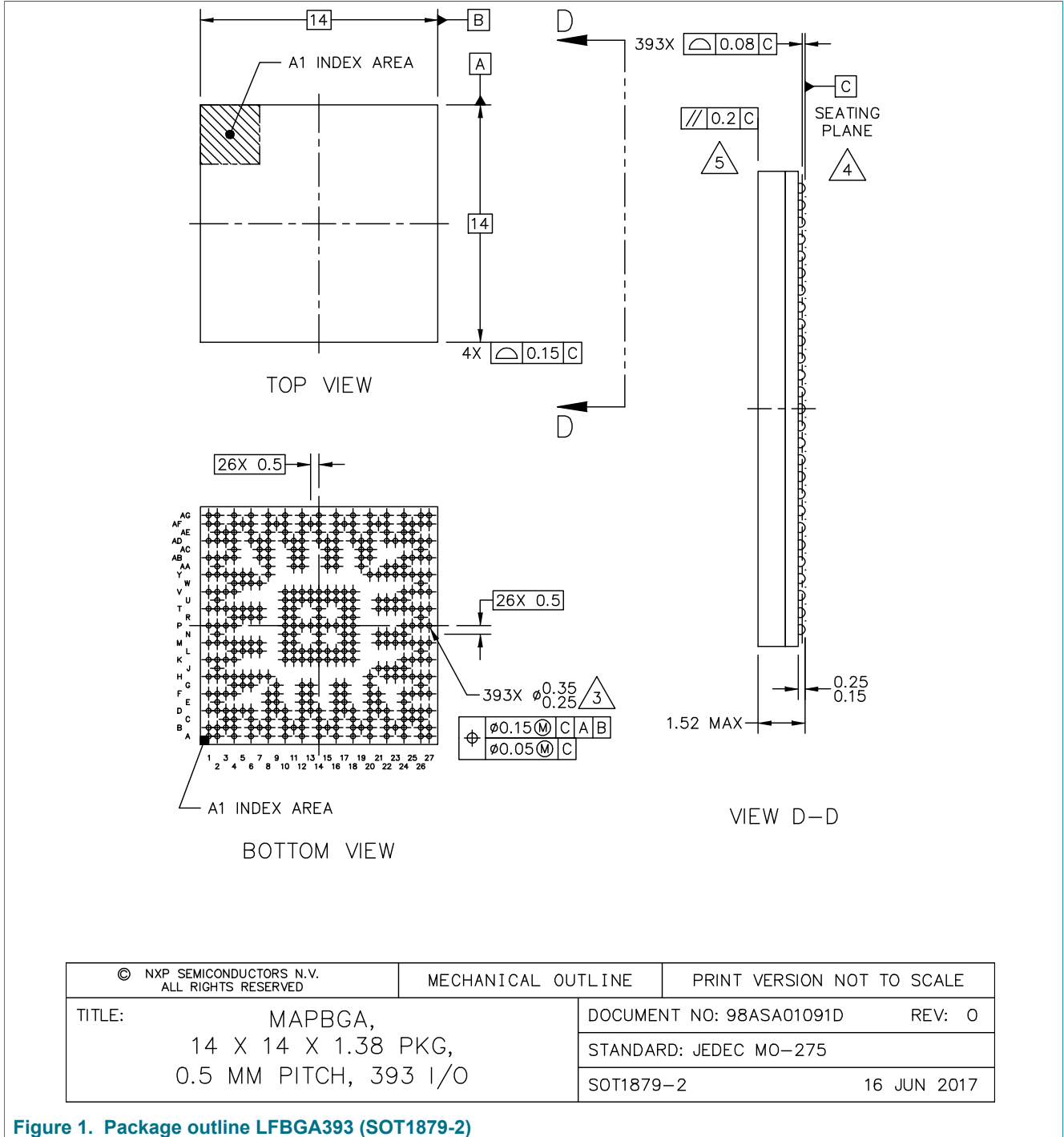


Figure 1. Package outline LFBGA393 (SOT1879-2)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: MAPBGA, 14 X 14 X 1.38 PKG, 0.5 MM PITCH, 393 I/O	DOCUMENT NO: 98ASA01091D		REV: 0
	STANDARD: JEDEC MO-275		
	SOT1879-2		16 JUN 2017

Figure 2. Package outline note LFBGA393 (SOT1879-2)

3 Legal information

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